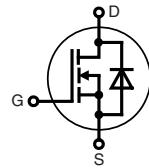


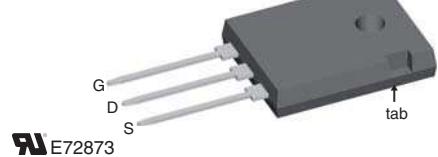
# CoolMOS™<sup>1)</sup> Power MOSFET

Low  $R_{DS(on)}$ , high  $V_{DSS}$   
Superjunction MOSFET

$V_{DSS}$  = 600 V  
 $I_{D25}$  = 47 A  
 $R_{DS(on)\ max}$  = 70 mΩ



TO-247



E72873

## MOSFET

Symbol	Conditions	Maximum Ratings		
$V_{DSS}$	$T_{VJ} = 25^\circ\text{C}$	600	V	
$V_{GS}$		$\pm 20$	V	
$I_{D25}$	$T_C = 25^\circ\text{C}$	47	A	
$I_{D100}$	$T_C = 100^\circ\text{C}$	30	A	
$E_{AS}$	single pulse $I_D = 10 \text{ A}; T_C = 25^\circ\text{C}$	1800	mJ	
$E_{AR}$	repetitive $I_D = 20 \text{ A}; T_C = 25^\circ\text{C}$	tbd	mJ	
$dV/dt$	MOSFET dV/dt ruggedness $V_{DS} = 0 \dots 480 \text{ V}$	tbd	V/ns	

## Symbol Conditions

## Characteristic Values

( $T_{VJ} = 25^\circ\text{C}$ , unless otherwise specified)

		min.	typ.	max.
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}; I_D = I_{D100}$ <sup>①</sup>	60	70	mΩ
$V_{GS(th)}$	$V_{DS} = V_{GS}; I_D = 2 \text{ mA}$	2		4 V
$I_{DSS}$	$V_{DS} = V_{DSS}; V_{GS} = 0 \text{ V}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$		25 250	μA μA
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$		±100	nA
$C_{iss}$ $C_{oss}$	$\left. \begin{array}{l} V_{GS} = 0 \text{ V}; V_{DS} = 100 \text{ V} \\ f = 1 \text{ MHz} \end{array} \right\}$	tbd tbd		pF pF
$Q_g$ $Q_{gs}$ $Q_{gd}$	$\left. \begin{array}{l} V_{GS} = 0 \text{ to } 10 \text{ V}; V_{DS} = 350 \text{ V}; I_D = 40 \text{ A} \end{array} \right\}$	255 30 110	650	nC nC nC
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$\left. \begin{array}{l} V_{GS} = 10 \text{ V}; V_{DS} = 380 \text{ V} \\ I_D = 47 \text{ A}; R_G = 4.7 \Omega \end{array} \right\}$	20 27 111 10		ns ns ns ns
$R_{thJC}$			0.3	K/W

<sup>①</sup> Pulse test,  $t \leq 300 \mu\text{s}$ , duty cycle  $d \leq 2\%$

<sup>1)</sup> CoolMOS™ is a trademark of Infineon Technologies AG.

## Features

- 3rd generation Superjunction power MOSFET
  - high blocking capability
  - lowest resistance
  - avalanche rated for unclamped inductive switching (UIS)
  - low thermal resistance due to reduced chip thickness

## Applications

- Switched mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)
- Power factor correction (PFC)
- Welding
- Inductive heating

**Source-Drain Diode****Symbol    Conditions****Characteristic Values**(T<sub>VJ</sub> = 25°C, unless otherwise specified)

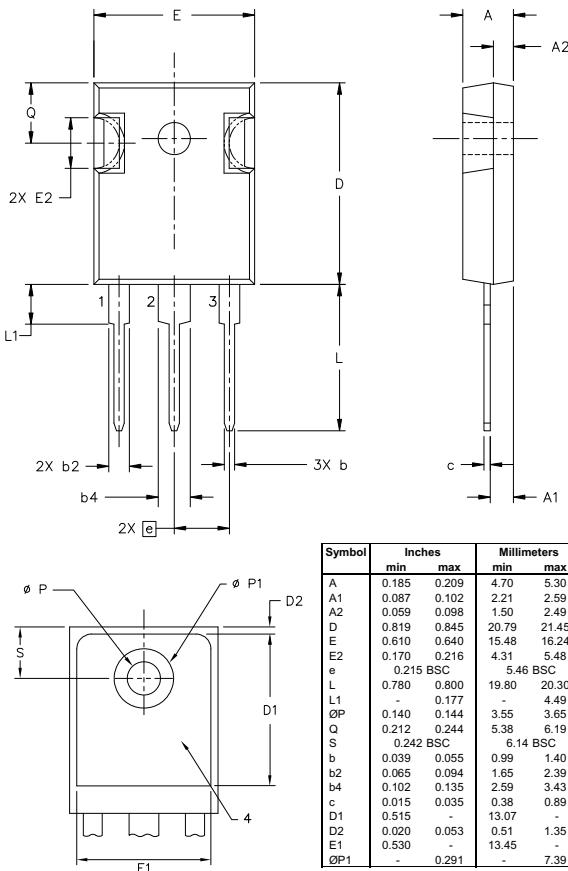
		min.	typ.	max.	
I <sub>S</sub>	V <sub>GS</sub> = 0 V				A
V <sub>SD</sub>	I <sub>F</sub> = 40 A; V <sub>GS</sub> = 0 V				V
t <sub>rr</sub> Q <sub>RM</sub> I <sub>RM</sub>	I <sub>F</sub> = 40 A; -di <sub>F</sub> /dt = 100 A/μs; V <sub>R</sub> = 640 V				ns μC A

**Component****Symbol    Conditions****Maximum Ratings**

T <sub>VJ</sub>	operating	-55...+150	°C
T <sub>stg</sub>		-55...+150	°C
M <sub>d</sub>	mounting torque	1.13	Nm

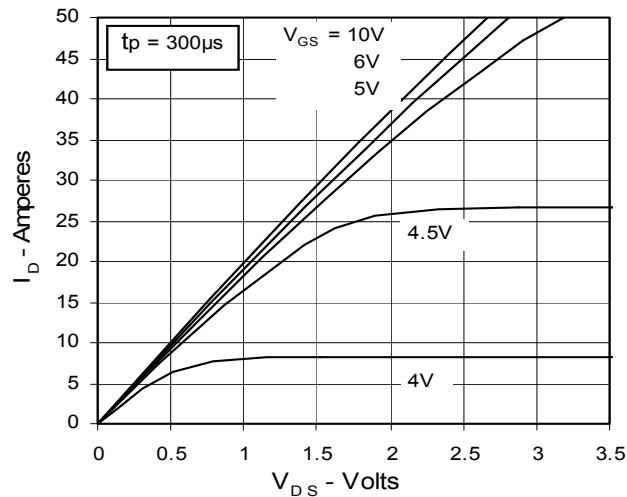
**Symbol    Conditions****Characteristic Values**

	min.	typ.	max.	
R <sub>thCH</sub>	with heatsink compound	tbd		K/W
Weight	2.7			g

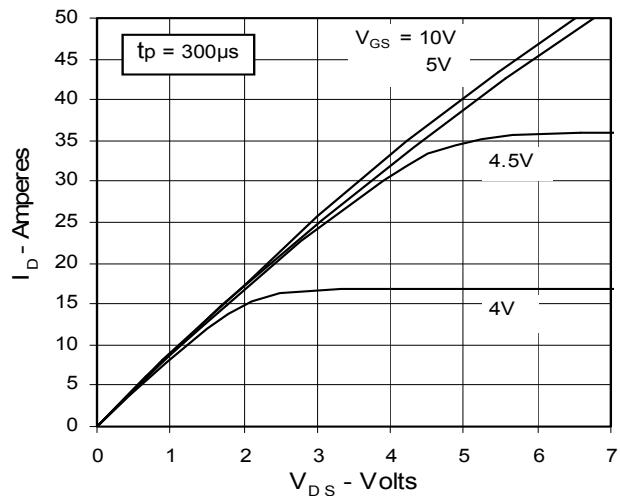
**TO-247 Outline**

Symbol	Inches	mm	inches	mm
A	0.185	0.209	4.70	5.30
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.50	2.49
D	0.819	0.845	20.79	21.45
E	0.610	0.640	15.48	16.24
E2	0.170	0.216	4.31	5.48
e	0.215 BSC		5.46 BSC	
L	0.780	0.800	19.80	20.30
L1	0.177		4.49	
ØP	0.140	0.144	3.55	3.65
Q	0.212	0.244	5.38	6.19
S	0.242 BSC		6.14 BSC	
b	0.039	0.055	0.99	1.40
b2	0.065	0.094	1.65	2.39
b4	0.102	0.135	2.59	3.43
c	0.015	0.035	0.38	0.89
D1	0.515	-	13.07	-
D2	0.020	0.053	0.51	1.35
E1	0.530	-	13.45	-
ØP1	-	0.291	-	7.39

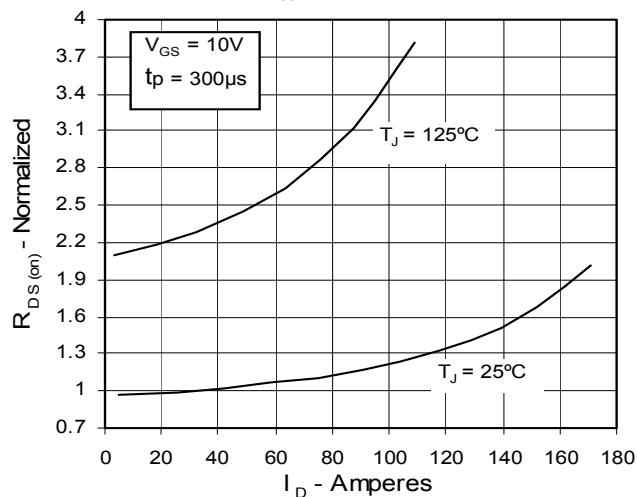
**Fig. 1. Output Characteristics  
@ 25 Deg. C**



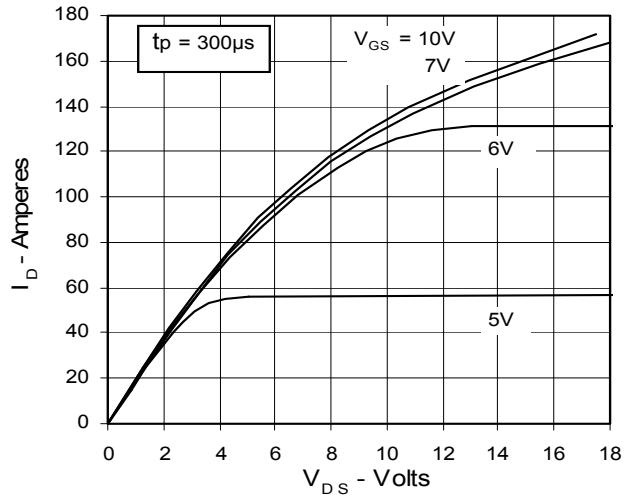
**Fig. 3. Output Characteristics  
@ 125 Deg. C**



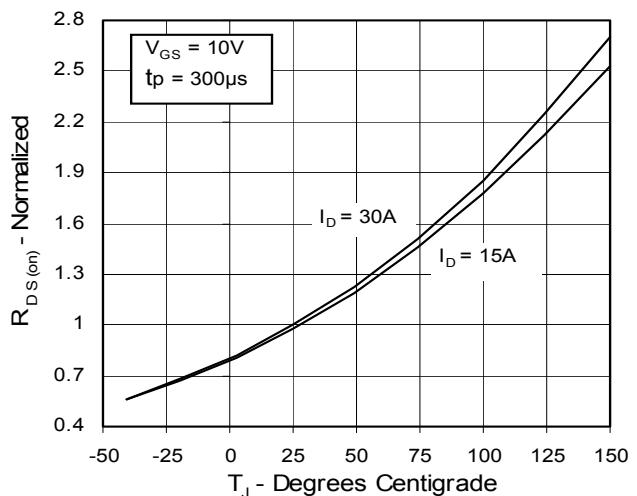
**Fig. 5.  $R_{DS(on)}$  Normalized to  
 $I_{D100}$  Value vs.  $I_D$**



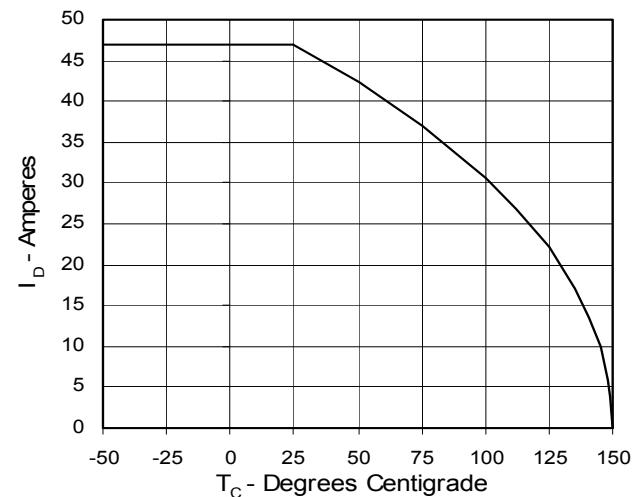
**Fig. 2. Extended Output Characteristics  
@ 25 deg. C**

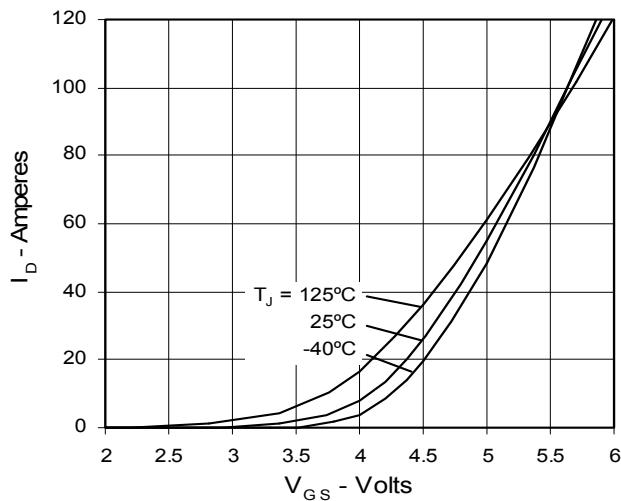
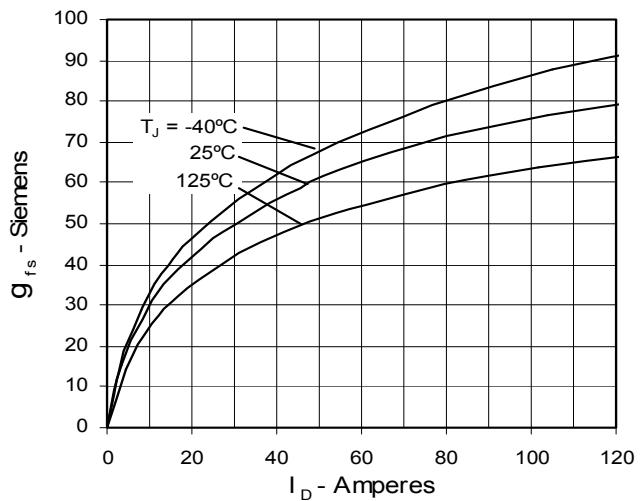
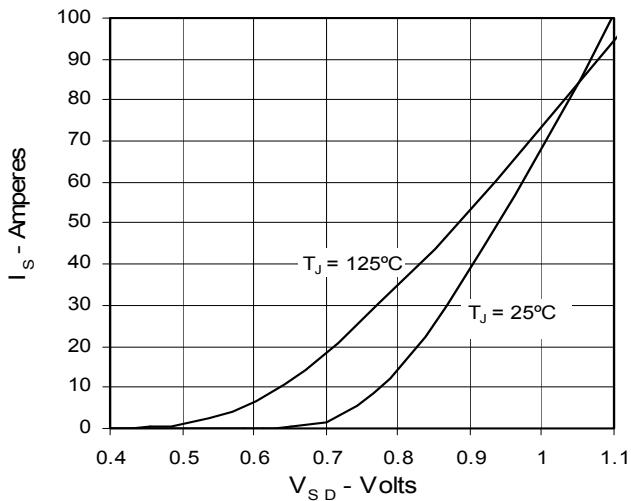
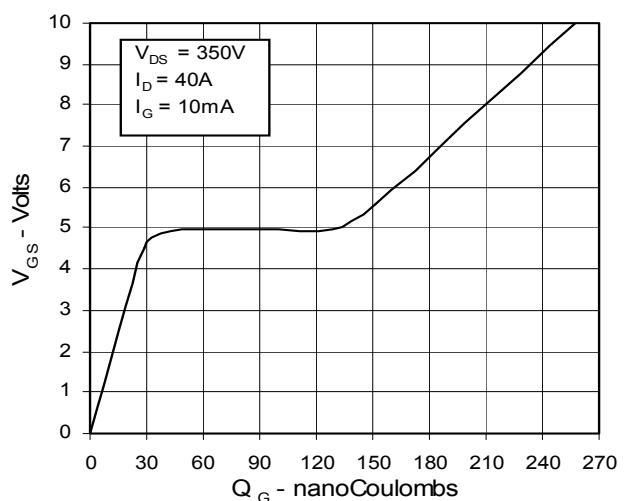
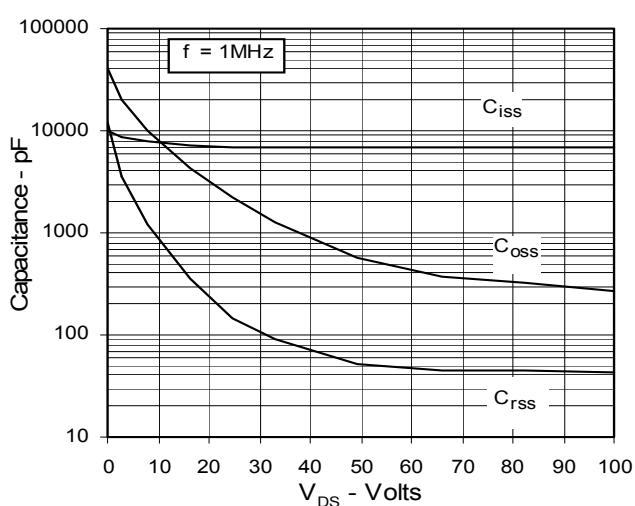


**Fig. 4.  $R_{DS(on)}$  Normalized to  $I_{D100}$  Value  
vs. Junction Temperature**



**Fig. 6. Drain Current vs. Case  
Temperature**



**Fig. 7. Input Admittance****Fig. 8. Transconductance****Fig. 9. Source Current vs. Source-To-Drain Voltage****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Maximum Transient Thermal Resistance**